Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	66MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (4)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 95°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/kmpc860encvr66d4

2 Features

The following list summarizes the key MPC860 features:

- Embedded single-issue, 32-bit core (implementing the Power Architecture technology) with thirty-two 32-bit general-purpose registers (GPRs)
  - The core performs branch prediction with conditional prefetch without conditional execution.
  - 4- or 8-Kbyte data cache and 4- or 16-Kbyte instruction cache (see Table 1)
    - 16-Kbyte instruction caches are four-way, set-associative with 256 sets; 4-Kbyte instruction caches are two-way, set-associative with 128 sets.
    - 8-Kbyte data caches are two-way, set-associative with 256 sets; 4-Kbyte data caches are two-way, set-associative with 128 sets.
    - Cache coherency for both instruction and data caches is maintained on 128-bit (4-word) cache blocks.
    - Caches are physically addressed, implement a least recently used (LRU) replacement algorithm, and are lockable on a cache block basis.
  - MMUs with 32-entry TLB, fully-associative instruction, and data TLBs
  - MMUs support multiple page sizes of 4-, 16-, and 512-Kbytes, and 8-Mbytes; 16 virtual address spaces and 16 protection groups
  - Advanced on-chip-emulation debug mode
- Up to 32-bit data bus (dynamic bus sizing for 8, 16, and 32 bits)
- 32 address lines
- Operates at up to 80 MHz
- Memory controller (eight banks)
  - Contains complete dynamic RAM (DRAM) controller
  - Each bank can be a chip select or $\overline{\text{RAS}}$ to support a DRAM bank.
  - Up to 15 wait states programmable per memory bank
  - Glueless interface to DRAM, SIMMS, SRAM, EPROM, Flash EPROM, and other memory devices
  - DRAM controller programmable to support most size and speed memory interfaces
  - Four $\overline{\text{CAS}}$ lines, four $\overline{\text{WE}}$ lines, and one $\overline{\text{OE}}$ line
  - Boot chip-select available at reset (options for 8-, 16-, or 32-bit memory)
  - Variable block sizes (32 Kbytes to 256 Mbytes)
  - Selectable write protection
  - On-chip bus arbitration logic
- General-purpose timers
  - Four 16-bit timers or two 32-bit timers
  - Gate mode can enable/disable counting
  - Interrupt can be masked on reference match and event capture.

7 Thermal Calculation and Measurement

For the following discussions, $P_D = (V_{DD} \times I_{DD}) + PI/O$, where PI/O is the power dissipation of the I/O drivers.

7.1 Estimation with Junction-to-Ambient Thermal Resistance

An estimation of the chip junction temperature, T_J, in ºC can be obtained from the equation:

$$T_J = T_A + (R_{\theta JA} \times P_D)$$

where:

T_A = ambient temperature (ºC)
$R_{\theta JA}$ = package junction-to-ambient thermal resistance (ºC/W)
P_D = power dissipation in package

The junction-to-ambient thermal resistance is an industry standard value which provides a quick and easy estimation of thermal performance. However, the answer is only an estimate; test cases have demonstrated that errors of a factor of two (in the quantity $T_J - T_A$) are possible.

7.2 Estimation with Junction-to-Case Thermal Resistance

Historically, the thermal resistance has frequently been expressed as the sum of a junction-to-case thermal resistance and a case-to-ambient thermal resistance:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$$

where:

$R_{\theta JA}$ = junction-to-ambient thermal resistance (ºC/W)
$R_{\theta JC}$ = junction-to-case thermal resistance (ºC/W)
$R_{\theta CA}$ = case-to-ambient thermal resistance (ºC/W)

$R_{\theta JC}$ is device related and cannot be influenced by the user. The user adjusts the thermal environment to affect the case-to-ambient thermal resistance, $R_{\theta CA}$. For instance, the user can change the airflow around the device, add a heat sink, change the mounting arrangement on the printed-circuit board, or change the thermal dissipation on the printed-circuit board surrounding the device. This thermal model is most useful for ceramic packages with heat sinks where some 90% of the heat flows through the case and the heat sink to the ambient environment. For most packages, a better model is required.

7.3 Estimation with Junction-to-Board Thermal Resistance

A simple package thermal model which has demonstrated reasonable accuracy (about 20%) is a two-resistor model consisting of a junction-to-board and a junction-to-case thermal resistance. The junction-to-case thermal resistance covers the situation where a heat sink is used or where a substantial amount of heat is dissipated from the top of the package. The junction-to-board thermal resistance describes the thermal performance when most of the heat is conducted to the printed-circuit board. It has been observed that the thermal performance of most plastic packages, especially PBGA packages, is strongly dependent on the board temperature; see Figure 2.

Table 7. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B9	CLKOUT to A(0:31), BADDR(28:30), RD/WR, BURST, D(0:31), DP(0:3), TSIZ(0:1), REG, RSV, AT(0:3), PTR High-Z	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.04	ns
B11	CLKOUT to TS, BB assertion	7.58	13.58	6.25	12.25	5.00	11.00	3.80	11.29	ns
B11a	CLKOUT to TA, BI assertion (when driven by the memory controller or PCMCIA interface)	2.50	9.25	2.50	9.25	2.50	9.25	2.50	9.75	ns
B12	CLKOUT to TS, BB negation	7.58	14.33	6.25	13.00	5.00	11.75	3.80	8.54	ns
B12a	CLKOUT to TA, BI negation (when driven by the memory controller or PCMCIA interface)	2.50	11.00	2.50	11.00	2.50	11.00	2.50	9.00	ns
B13	CLKOUT to TS, BB High-Z	7.58	21.58	6.25	20.25	5.00	19.00	3.80	14.04	ns
B13a	CLKOUT to TA, BI High-Z (when driven by the memory controller or PCMCIA interface)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B14	CLKOUT to TEA assertion	2.50	10.00	2.50	10.00	2.50	10.00	2.50	9.00	ns
B15	CLKOUT to TEA High-Z	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B16	TA, BI valid to CLKOUT (setup time)	9.75	—	9.75	—	9.75	—	6.00	—	ns
B16a	TEA, KR, RETRY, CR valid to CLKOUT (setup time)	10.00	—	10.00	—	10.00	—	4.50	—	ns
B16b	BB, BG, BR, valid to CLKOUT (setup time)[5]	8.50	—	8.50	—	8.50	—	4.00	—	ns
B17	CLKOUT to TA, TEA, BI, BB, BG, BR valid (hold time)	1.00	—	1.00	—	1.00	—	2.00	—	ns
B17a	CLKOUT to KR, RETRY, CR valid (hold time)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B18	D(0:31), DP(0:3) valid to CLKOUT rising edge (setup time)[6]	6.00	—	6.00	—	6.00	—	6.00	—	ns
B19	CLKOUT rising edge to D(0:31), DP(0:3) valid (hold time)[6]	1.00	—	1.00	—	1.00	—	2.00	—	ns
B20	D(0:31), DP(0:3) valid to CLKOUT falling edge (setup time)[7]	4.00	—	4.00	—	4.00	—	4.00	—	ns
B21	CLKOUT falling edge to D(0:31), DP(0:3) valid (hold time)[7]	2.00	—	2.00	—	2.00	—	2.00	—	ns
B22	CLKOUT rising edge to CS asserted GPCM ACS = 00	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.04	ns
B22a	CLKOUT falling edge to CS asserted GPCM ACS = 10, TRLX = 0	—	8.00	—	8.00	—	8.00	—	8.00	ns
B22b	CLKOUT falling edge to CS asserted GPCM ACS = 11, TRLX = 0, EBDF = 0	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.54	ns
B22c	CLKOUT falling edge to CS asserted GPCM ACS = 11, TRLX = 0, EBDF = 1	10.86	17.99	8.88	16.00	7.00	14.13	5.18	12.31	ns

Table 7. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B35	A(0:31), BADDR(28:30) to $\overline{\text{CS}}$ valid—as requested by control bit BST4 in the corresponding word in UPM	5.58	—	4.25	—	3.00	—	1.79	—	ns
B35a	A(0:31), BADDR(28:30), and D(0:31) to $\overline{\text{BS}}$ valid—as requested by control bit BST1 in the corresponding word in UPM	13.15	—	10.50	—	8.00	—	5.58	—	ns
B35b	A(0:31), BADDR(28:30), and D(0:31) to $\overline{\text{BS}}$ valid—as requested by control bit BST2 in the corresponding word in UPM	20.73	—	16.75	—	13.00	—	9.36	—	ns
B36	A(0:31), BADDR(28:30), and D(0:31) to $\overline{\text{GPL}}$ valid—as requested by control bit GxT4 in the corresponding word in UPM	5.58	—	4.25	—	3.00	—	1.79	—	ns
B37	UPWAIT valid to CLKOUT falling edge[9]	6.00	—	6.00	—	6.00	—	6.00	—	ns
B38	CLKOUT falling edge to UPWAIT valid[9]	1.00	—	1.00	—	1.00	—	1.00	—	ns
B39	$\overline{\text{AS}}$ valid to CLKOUT rising edge[10]	7.00	—	7.00	—	7.00	—	7.00	—	ns
B40	A(0:31), TSIZ(0:1), RD/$\overline{\text{WR}}$, $\overline{\text{BURST}}$, valid to CLKOUT rising edge	7.00	—	7.00	—	7.00	—	7.00	—	ns
B41	$\overline{\text{TS}}$ valid to CLKOUT rising edge (setup time)	7.00	—	7.00	—	7.00	—	7.00	—	ns
B42	CLKOUT rising edge to $\overline{\text{TS}}$ valid (hold time)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B43	$\overline{\text{AS}}$ negation to memory controller signals negation	—	TBD	—	TBD	—	TBD	—	TBD	ns

[1] Phase and frequency jitter performance results are only valid if the input jitter is less than the prescribed value.

[2] If the rate of change of the frequency of EXTAL is slow (that is, it does not jump between the minimum and maximum values in one cycle) or the frequency of the jitter is fast (that is, it does not stay at an extreme value for a long time) then the maximum allowed jitter on EXTAL can be up to 2%.

[3] The timings specified in B4 and B5 are based on full strength clock.

[4] The timing for $\overline{\text{BR}}$ output is relevant when the MPC860 is selected to work with external bus arbiter. The timing for $\overline{\text{BG}}$ output is relevant when the MPC860 is selected to work with internal bus arbiter.

[5] The timing required for $\overline{\text{BR}}$ input is relevant when the MPC860 is selected to work with internal bus arbiter. The timing for $\overline{\text{BG}}$ input is relevant when the MPC860 is selected to work with external bus arbiter.

[6] The D(0:31) and DP(0:3) input timings B18 and B19 refer to the rising edge of the CLKOUT in which the $\overline{\text{TA}}$ input signal is asserted.

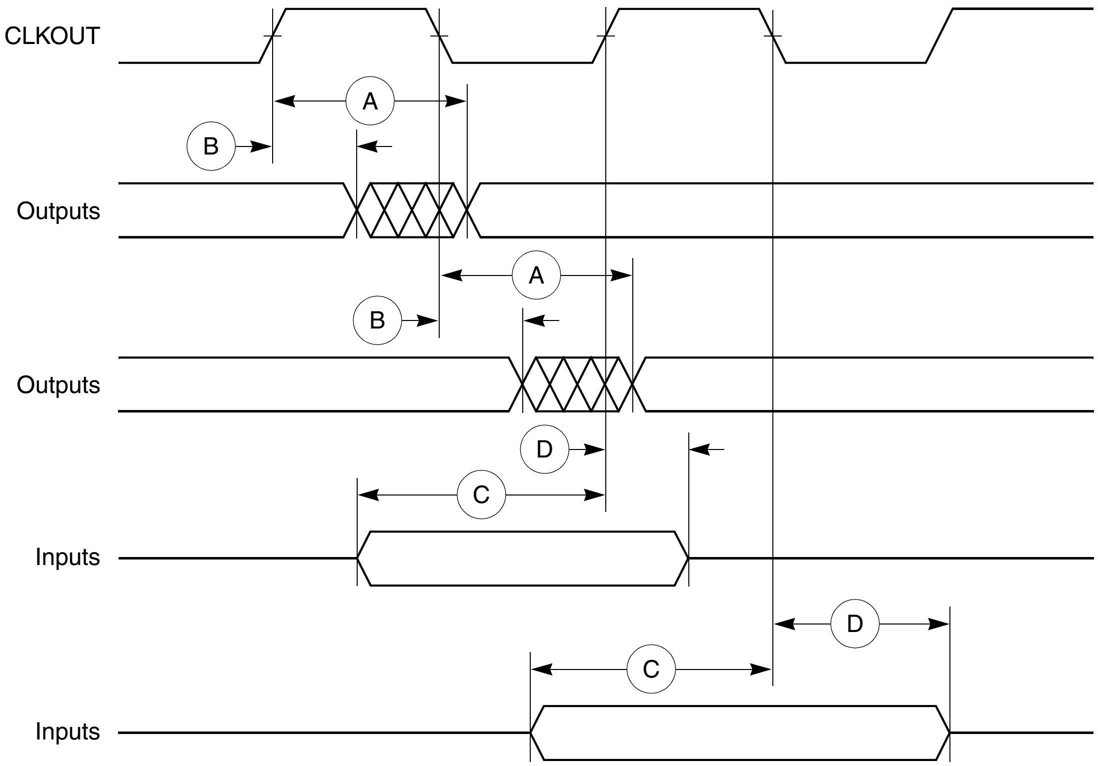
[7] The D(0:31) and DP(0:3) input timings B20 and B21 refer to the falling edge of the CLKOUT. This timing is valid only for read accesses controlled by chip-selects under control of the UPM in the memory controller, for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

[8] The timing B30 refers to $\overline{\text{CS}}$ when ACS = 00 and to $\overline{\text{WE}}$(0:3) when CSNT = 0.

[9] The signal UPWAIT is considered asynchronous to the CLKOUT and synchronized internally. The timings specified in B37 and B38 are specified to enable the freeze of the UPM output signals as described in Figure 18.

[10] The $\overline{\text{AS}}$ signal is considered asynchronous to the CLKOUT. The timing B39 is specified in order to allow the behavior specified in Figure 21.

Figure 3 is the control timing diagram.



Ⓐ Maximum output delay specification.

Ⓑ Minimum output hold time.

Ⓒ Minimum input setup time specification.

Ⓓ Minimum input hold time specification.

Figure 3. Control Timing

Figure 4 provides the timing for the external clock.

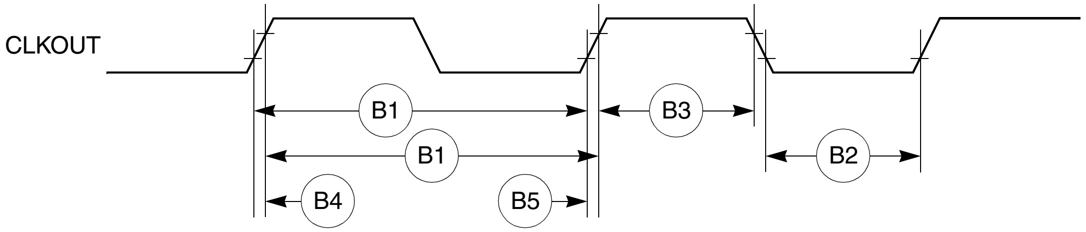


Figure 4. External Clock Timing

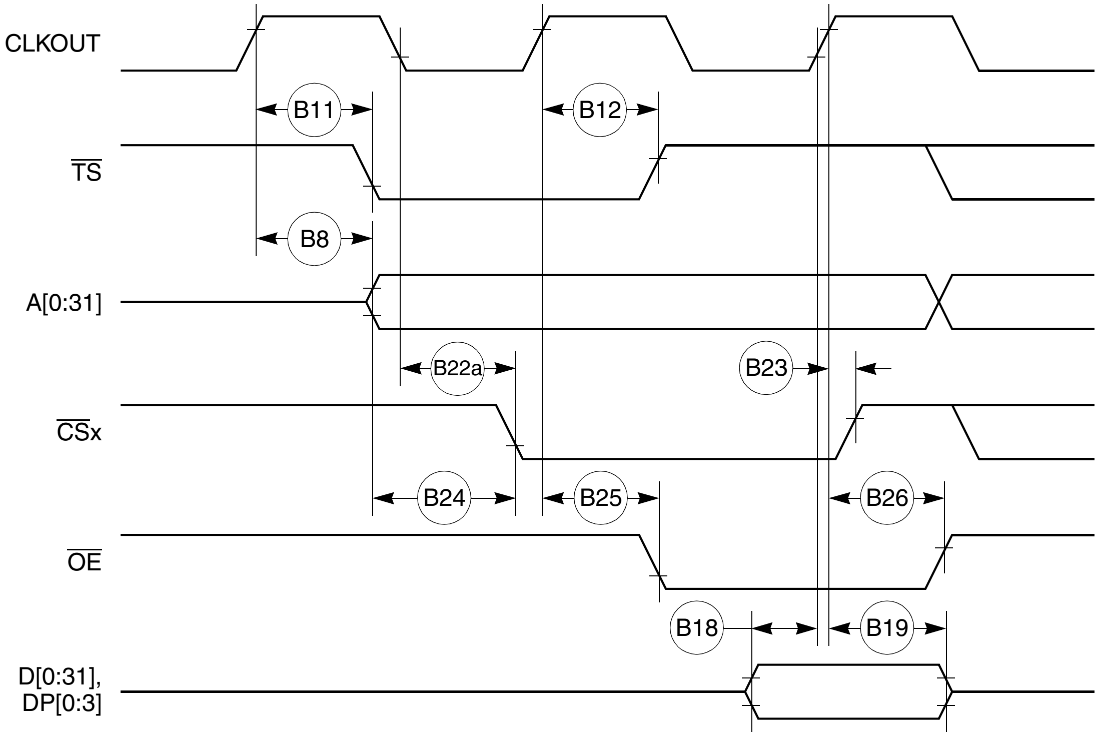


Figure 11. External Bus Read Timing (GPCM Controlled—TRLX = 0, ACS = 10)

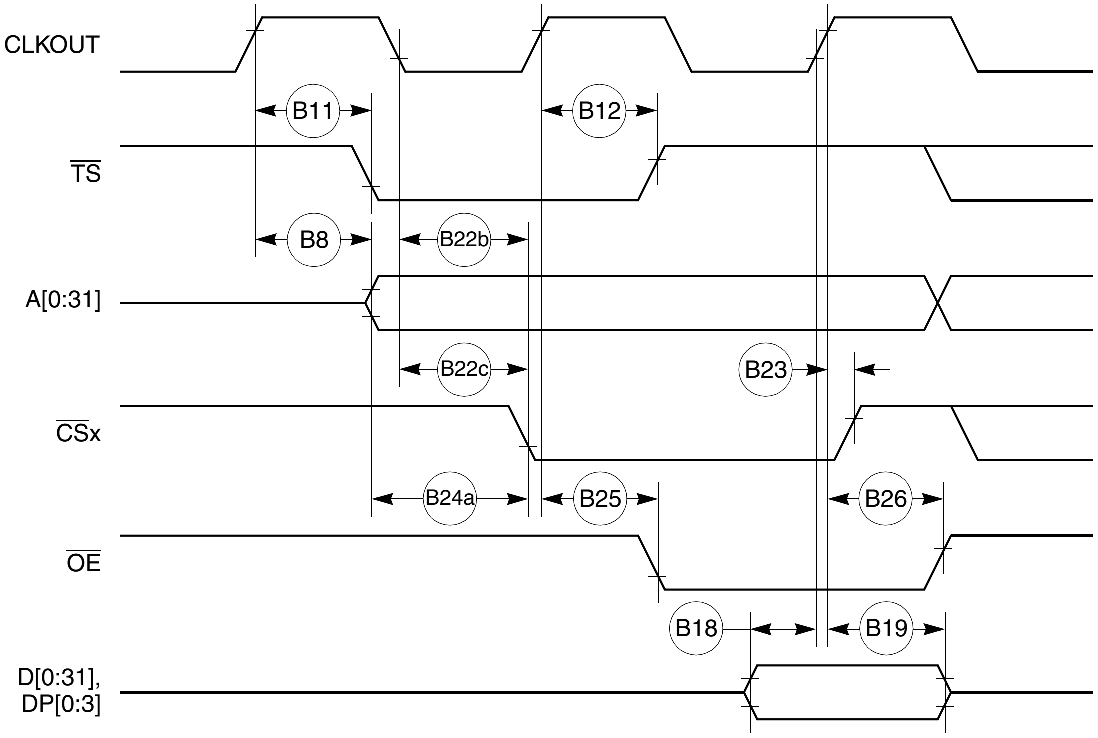


Figure 12. External Bus Read Timing (GPCM Controlled—TRLX = 0, ACS = 11)

Figure 20 provides the timing for the synchronous external master access controlled by the GPCM.

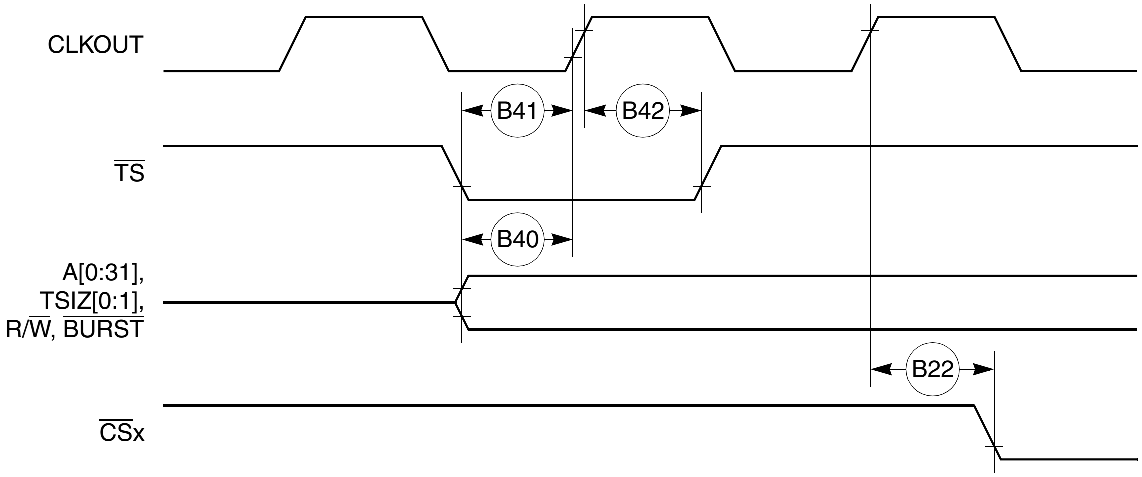


Figure 20. Synchronous External Master Access Timing (GPCM Handled ACS = 00)

Figure 21 provides the timing for the asynchronous external master memory access controlled by the GPCM.

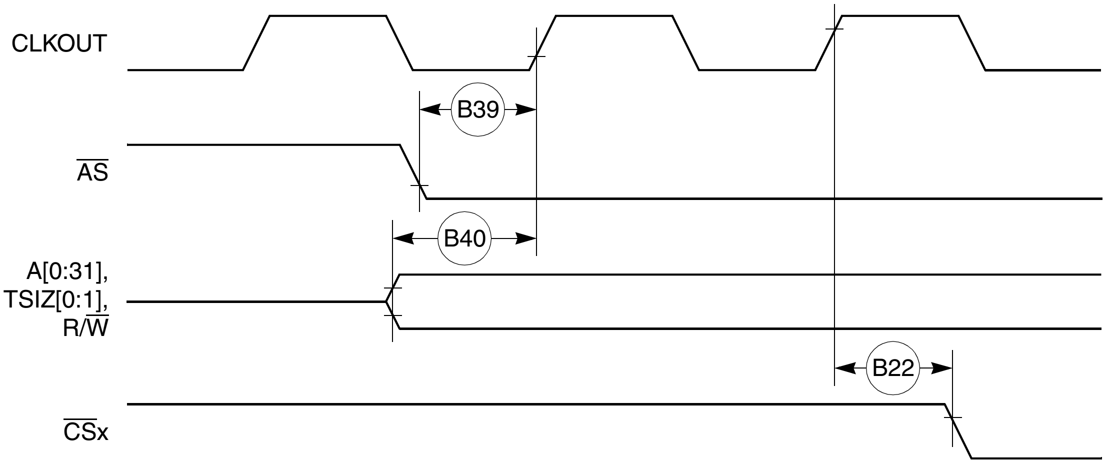


Figure 21. Asynchronous External Master Memory Access Timing (GPCM Controlled—ACS = 00)

Figure 22 provides the timing for the asynchronous external master control signals negation.

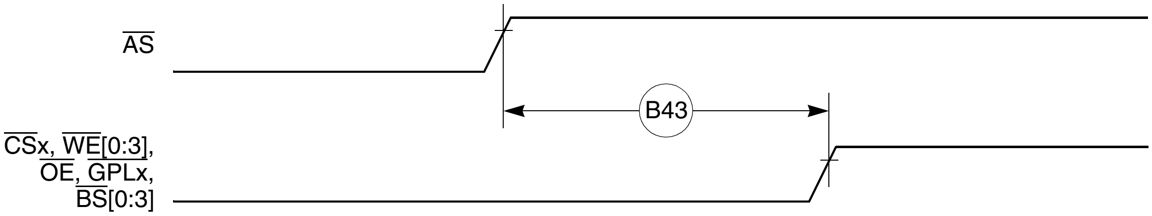


Figure 22. Asynchronous External Master—Control Signals Negation Timing

Table 9 shows the PCMCIA timing for the MPC860.

Table 9. PCMCIA Timing

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
P44	A(0:31), $\overline{\text{REG}}$ valid to PCMCIA Strobe asserted[1]	20.73	—	16.75	—	13.00	—	9.36	—	ns
P45	A(0:31), $\overline{\text{REG}}$ valid to ALE negation[1]	28.30	—	23.00	—	18.00	—	13.15	—	ns
P46	CLKOUT to $\overline{\text{REG}}$ valid	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P47	CLKOUT to $\overline{\text{REG}}$ invalid	8.58	—	7.25	—	6.00	—	4.84	—	ns
P48	CLKOUT to $\overline{\text{CE1}}$, $\overline{\text{CE2}}$ asserted	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P49	CLKOUT to $\overline{\text{CE1}}$, $\overline{\text{CE2}}$ negated	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P50	CLKOUT to $\overline{\text{PCOE}}$, $\overline{\text{IORD}}$, $\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ assert time	—	11.00		11.00	—	11.00	—	11.00	ns
P51	CLKOUT to $\overline{\text{PCOE}}$, $\overline{\text{IORD}}$, $\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ negate time	2.00	11.00	2.00	11.00	2.00	11.00	2.00	11.00	ns
P52	CLKOUT to ALE assert time	7.58	15.58	6.25	14.25	5.00	13.00	3.79	10.04	ns
P53	CLKOUT to ALE negate time	—	15.58		14.25	—	13.00	—	11.84	ns
P54	$\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ negated to D(0:31) invalid[1]	5.58	—	4.25	—	3.00	—	1.79	—	ns
P55	$\overline{\text{WAITA}}$ and $\overline{\text{WAITB}}$ valid to CLKOUT rising edge[1]	8.00	—	8.00	—	8.00	—	8.00	—	ns
P56	CLKOUT rising edge to $\overline{\text{WAITA}}$ and $\overline{\text{WAITB}}$ invalid[1]	2.00	—	2.00	—	2.00	—	2.00	—	ns

[1] PSST = 1. Otherwise add PSST times cycle time.
PSHT = 0. Otherwise add PSHT times cycle time.

These synchronous timings define when the $\overline{\text{WAITx}}$ signals are detected in order to freeze (or relieve) the PCMCIA current cycle. The $\overline{\text{WAITx}}$ assertion will be effective only if it is detected 2 cycles before the PSL timer expiration. See Chapter 16, “PCMCIA Interface,” in the *MPC860 PowerQUICC™ Family User’s Manual*.

Table 12 shows the reset timing for the MPC860.

Table 12. Reset Timing

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
R69	CLKOUT to $\overline{\text{HRESET}}$ high impedance	—	20.00	—	20.00	—	20.00	—	20.00	ns
R70	CLKOUT to $\overline{\text{SRESET}}$ high impedance	—	20.00	—	20.00	—	20.00	—	20.00	ns
R71	$\overline{\text{RSTCONF}}$ pulse width	515.15	—	425.00		340.00	—	257.58	—	ns
R72	—	—	—	—	—	—	—	—	—	
R73	Configuration data to HRESET rising edge setup time	504.55	—	425.00	—	350.00	—	277.27	—	ns
R74	Configuration data to $\overline{\text{RSTCONF}}$ rising edge setup time	350.00	—	350.00	—	350.00	—	350.00	—	ns
R75	Configuration data hold time after $\overline{\text{RSTCONF}}$ negation	0.00	—	0.00	—	0.00	—	0.00	—	ns
R76	Configuration data hold time after $\overline{\text{HRESET}}$ negation	0.00	—	0.00	—	0.00	—	0.00	—	ns
R77	$\overline{\text{HRESET}}$ and $\overline{\text{RSTCONF}}$ asserted to data out drive	—	25.00		25.00	—	25.00	—	25.00	ns
R78	$\overline{\text{RSTCONF}}$ negated to data out high impedance	—	25.00	—	25.00	—	25.00	—	25.00	ns
R79	CLKOUT of last rising edge before chip three-state $\overline{\text{HRESET}}$ to data out high impedance	—	25.00	—	25.00	—	25.00	—	25.00	ns
R80	DSDI, DSCK setup	90.91	—	75.00	—	60.00	—	45.45	—	ns
R81	DSDI, DSCK hold time	0.00	—	0.00	—	0.00	—	0.00	—	ns
R82	$\overline{\text{SRESET}}$ negated to CLKOUT rising edge for DSDI and DSCK sample	242.42	—	200.00	—	160.00	—	121.21	—	ns

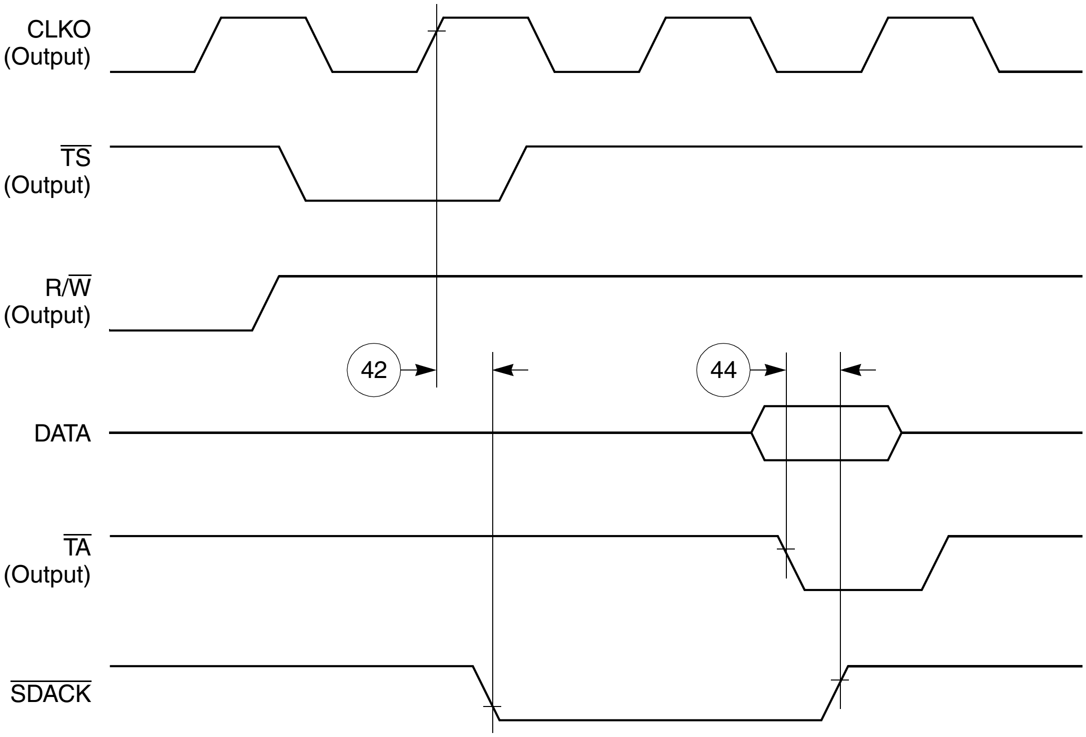


Figure 47. SDACK Timing Diagram—Peripheral Write, Internally-Generated TA

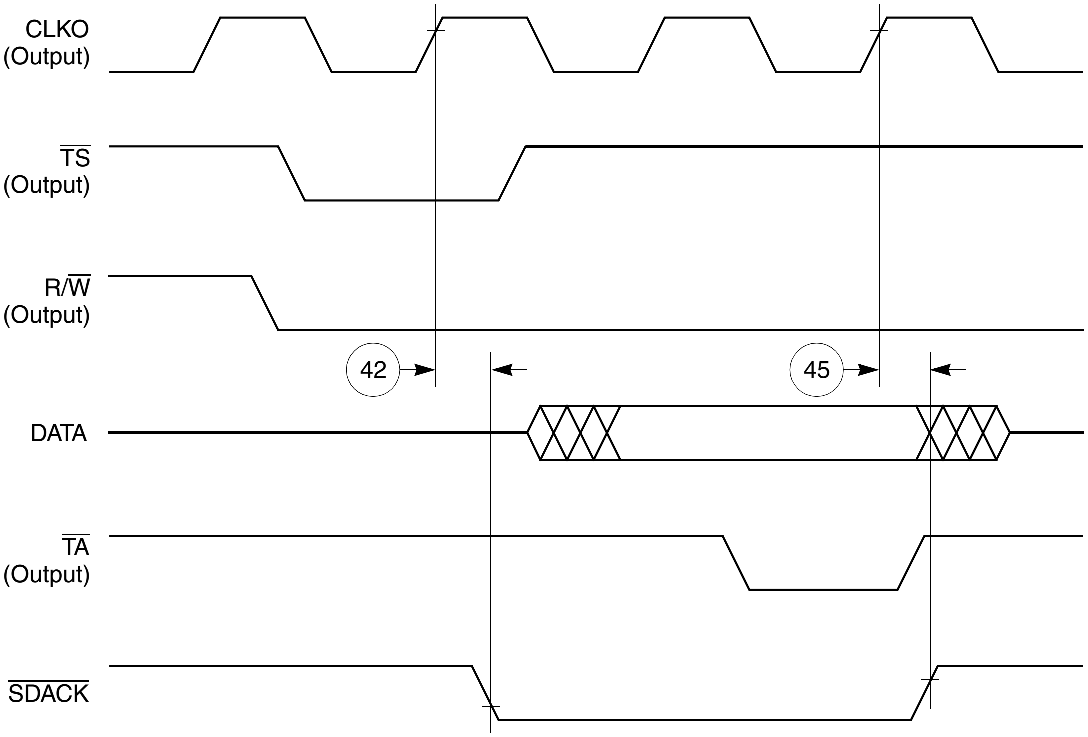


Figure 48. SDACK Timing Diagram—Peripheral Read, Internally-Generated TA

11.4 Baud Rate Generator AC Electrical Specifications

Table 17 provides the baud rate generator timings as shown in Figure 49.

Table 17. Baud Rate Generator Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
50	BRGO rise and fall time	—	10	ns
51	BRGO duty cycle	40	60	%
52	BRGO cycle	40	—	ns

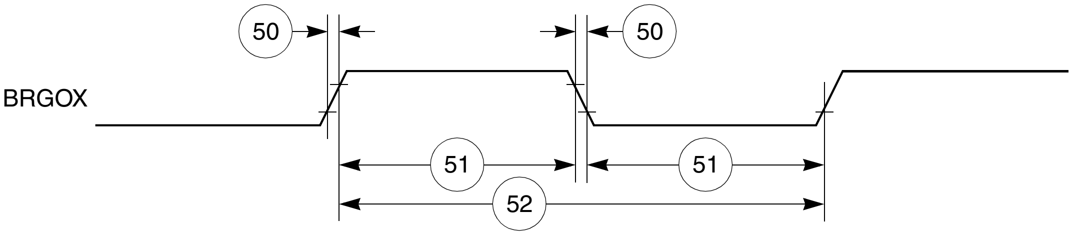


Figure 49. Baud Rate Generator Timing Diagram

11.5 Timer AC Electrical Specifications

Table 18 provides the general-purpose timer timings as shown in Figure 50.

Table 18. Timer Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
61	TIN/$\overline{\text{TGATE}}$ rise and fall time	10	—	ns
62	TIN/$\overline{\text{TGATE}}$ low time	1	—	CLK
63	TIN/$\overline{\text{TGATE}}$ high time	2	—	CLK
64	TIN/$\overline{\text{TGATE}}$ cycle time	3	—	CLK
65	CLKO low to $\overline{\text{TOUT}}$ valid	3	25	ns

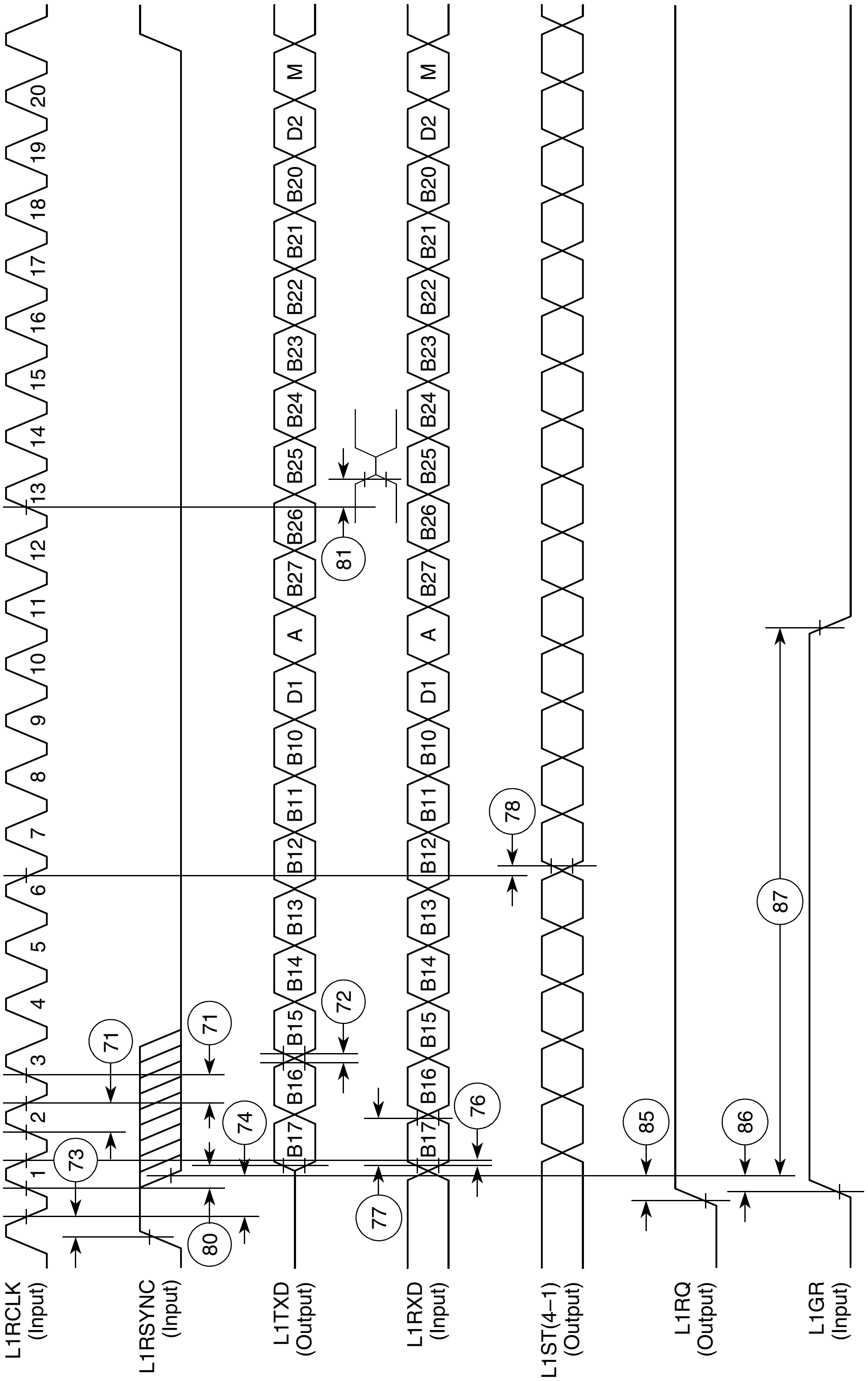


Figure 55. IDL Timing

11.7 SCC in NMSI Mode Electrical Specifications

Table 20 provides the NMSI external clock timing.

Table 20. NMSI External Clock Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
100	RCLK1 and TCLK1 width high[1]	1/SYNCCLK	—	ns
101	RCLK1 and TCLK1 width low	1/SYNCCLK + 5	—	ns
102	RCLK1 and TCLK1 rise/fall time	—	15.00	ns
103	TXD1 active delay (from TCLK1 falling edge)	0.00	50.00	ns
104	$\overline{\text{RTS1}}$ active/inactive delay (from TCLK1 falling edge)	0.00	50.00	ns
105	$\overline{\text{CTS1}}$ setup time to TCLK1 rising edge	5.00	—	ns
106	RXD1 setup time to RCLK1 rising edge	5.00	—	ns
107	RXD1 hold time from RCLK1 rising edge[2]	5.00	—	ns
108	$\overline{\text{CD1}}$ setup Time to RCLK1 rising edge	5.00	—	ns

[1] The ratios SYNCCLK/RCLK1 and SYNCCLK/TCLK1 must be greater than or equal to 2.25/1.

[2] Also applies to $\overline{\text{CD}}$ and $\overline{\text{CTS}}$ hold time when they are used as external sync signals.

Table 21 provides the NMSI internal clock timing.

Table 21. NMSI Internal Clock Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
100	RCLK1 and TCLK1 frequency[1]	0.00	SYNCCLK/3	MHz
102	RCLK1 and TCLK1 rise/fall time	—	—	ns
103	TXD1 active delay (from TCLK1 falling edge)	0.00	30.00	ns
104	$\overline{\text{RTS1}}$ active/inactive delay (from TCLK1 falling edge)	0.00	30.00	ns
105	$\overline{\text{CTS1}}$ setup time to TCLK1 rising edge	40.00	—	ns
106	RXD1 setup time to RCLK1 rising edge	40.00	—	ns
107	RXD1 hold time from RCLK1 rising edge[2]	0.00	—	ns
108	$\overline{\text{CD1}}$ setup time to RCLK1 rising edge	40.00	—	ns

[1] The ratios SYNCCLK/RCLK1 and SYNCCLK/TCLK1 must be greater than or equal to 3/1.

[2] Also applies to $\overline{\text{CD}}$ and $\overline{\text{CTS}}$ hold time when they are used as external sync signals.

Figure 56 through Figure 58 show the NMSI timings.

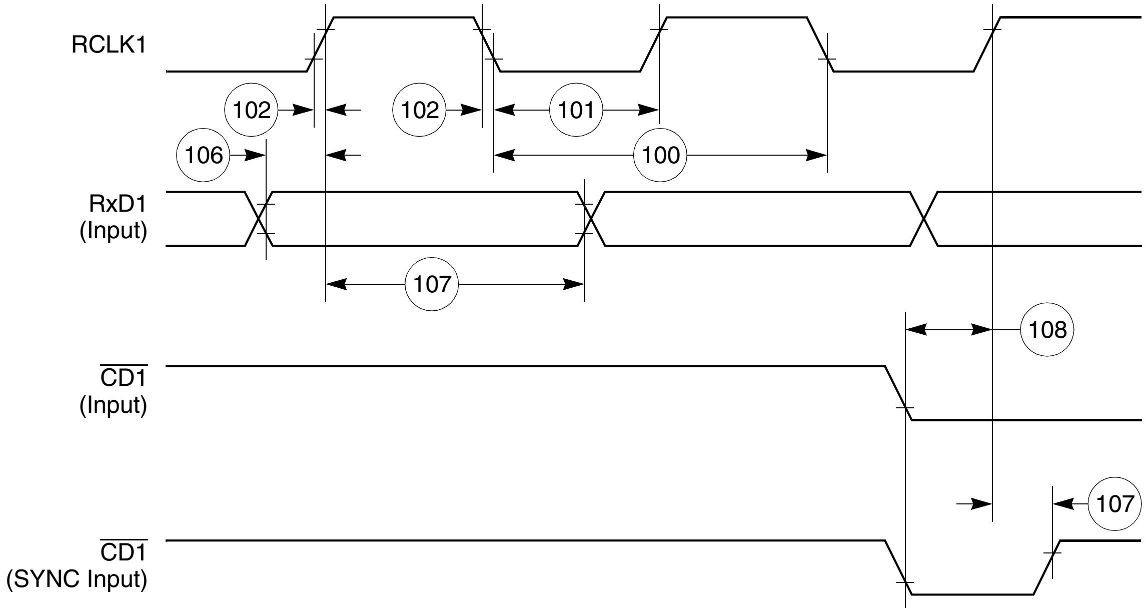


Figure 56. SCC NMSI Receive Timing Diagram

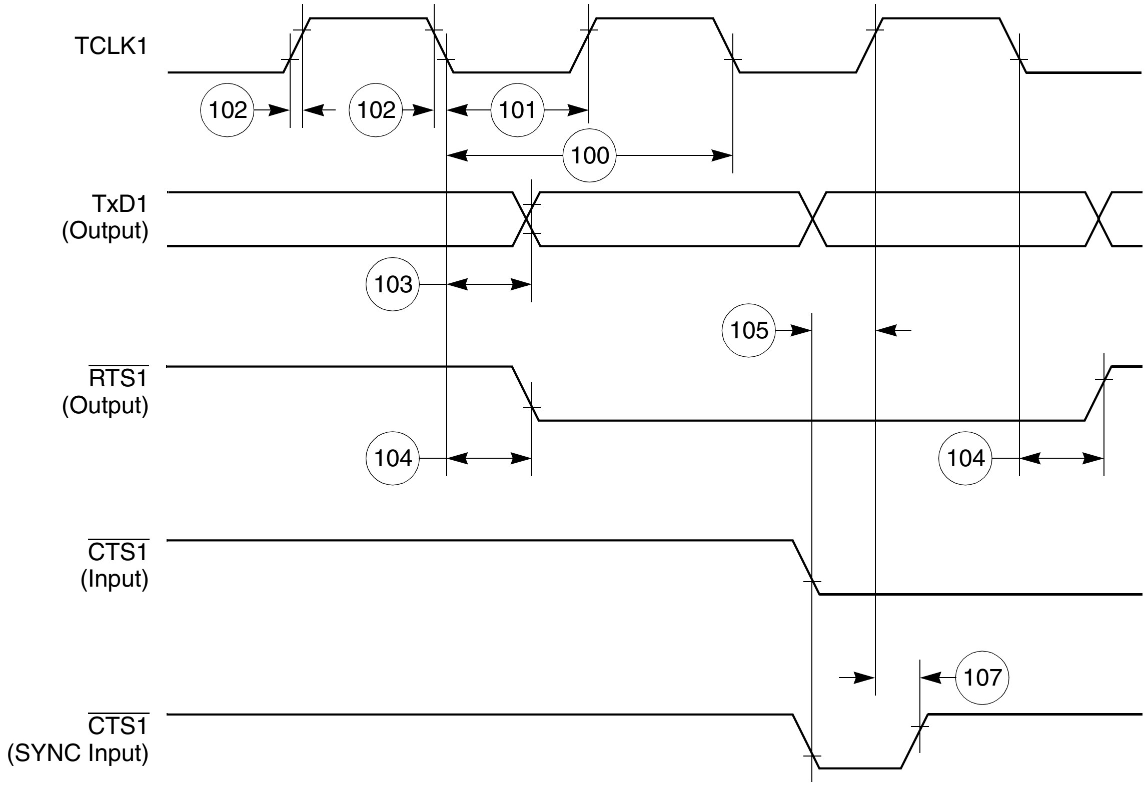


Figure 57. SCC NMSI Transmit Timing Diagram

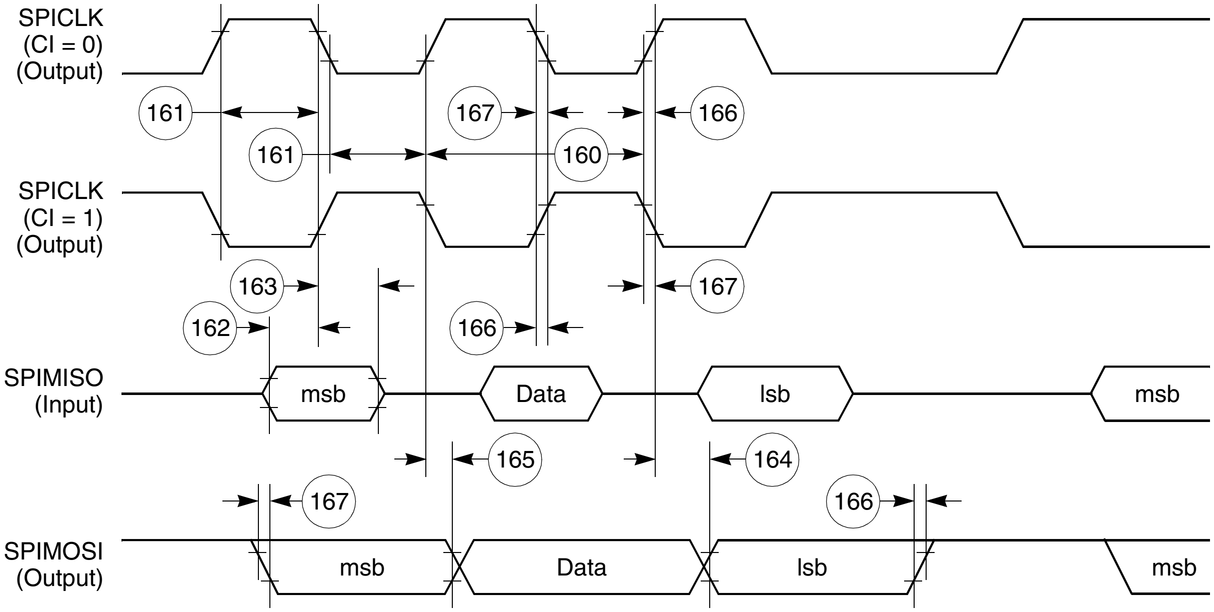


Figure 66. SPI Master (CP = 1) Timing Diagram

11.11 SPI Slave AC Electrical Specifications

Table 25 provides the SPI slave timings as shown in Figure 67 and Figure 68.

Table 25. SPI Slave Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
170	Slave cycle time	2	—	t_{cyc}
171	Slave enable lead time	15	—	ns
172	Slave enable lag time	15	—	ns
173	Slave clock (SPICLK) high or low time	1	—	t_{cyc}
174	Slave sequential transfer delay (does not require deselect)	1	—	t_{cyc}
175	Slave data setup time (inputs)	20	—	ns
176	Slave data hold time (inputs)	20	—	ns
177	Slave access time	—	50	ns

13 FEC Electrical Characteristics

This section provides the AC electrical specifications for the Fast Ethernet controller (FEC). Note that the timing specifications for the MII signals are independent of system clock frequency (part speed designation). Also, MII signals use TTL signal levels compatible with devices operating at either 5.0 V or 3.3 V.

13.1 MII Receive Signal Timing (MII_RXD[3:0], MII_RX_DV, MII_RX_ER, MII_RX_CLK)

The receiver functions correctly up to a MII_RX_CLK maximum frequency of 25 MHz + 1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII_RX_CLK frequency – 1%.

Table 29 provides information on the MII receive signal timing.

Table 29. MII Receive Signal Timing

Num	Characteristic	Min	Max	Unit
M1	MII_RXD[3:0], MII_RX_DV, MII_RX_ER to MII_RX_CLK setup	5	—	ns
M2	MII_RX_CLK to MII_RXD[3:0], MII_RX_DV, MII_RX_ER hold	5	—	ns
M3	MII_RX_CLK pulse width high	35%	65%	MII_RX_CLK period
M4	MII_RX_CLK pulse width low	35%	65%	MII_RX_CLK period

Figure 72 shows MII receive signal timing.

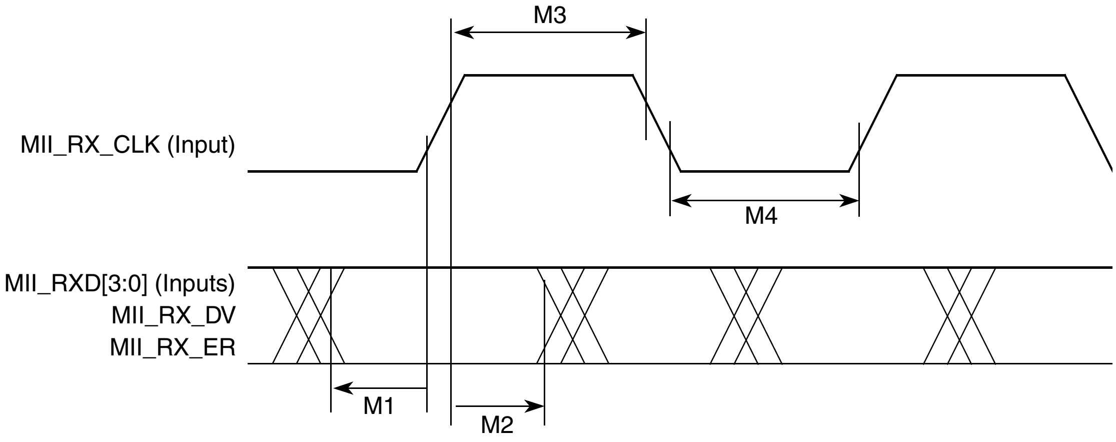


Figure 72. MII Receive Signal Timing Diagram

13.2 MII Transmit Signal Timing (MII_TXD[3:0], MII_TX_EN, MII_TX_ER, MII_TX_CLK)

The transmitter functions correctly up to a MII_TX_CLK maximum frequency of 25 MHz +1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII_TX_CLK frequency – 1%.

Table 30 provides information on the MII transmit signal timing.

Table 30. MII Transmit Signal Timing

Num	Characteristic	Min	Max	Unit
M5	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER invalid	5	—	ns
M6	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER valid	—	25	
M7	MII_TX_CLK pulse width high	35	65%	MII_TX_CLK period
M8	MII_TX_CLK pulse width low	35%	65%	MII_TX_CLK period

Figure 73 shows the MII transmit signal timing diagram.

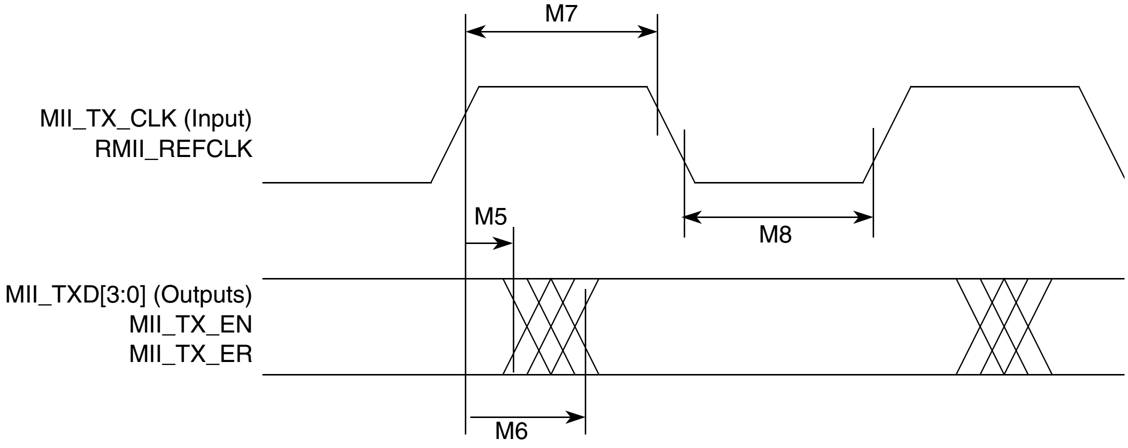


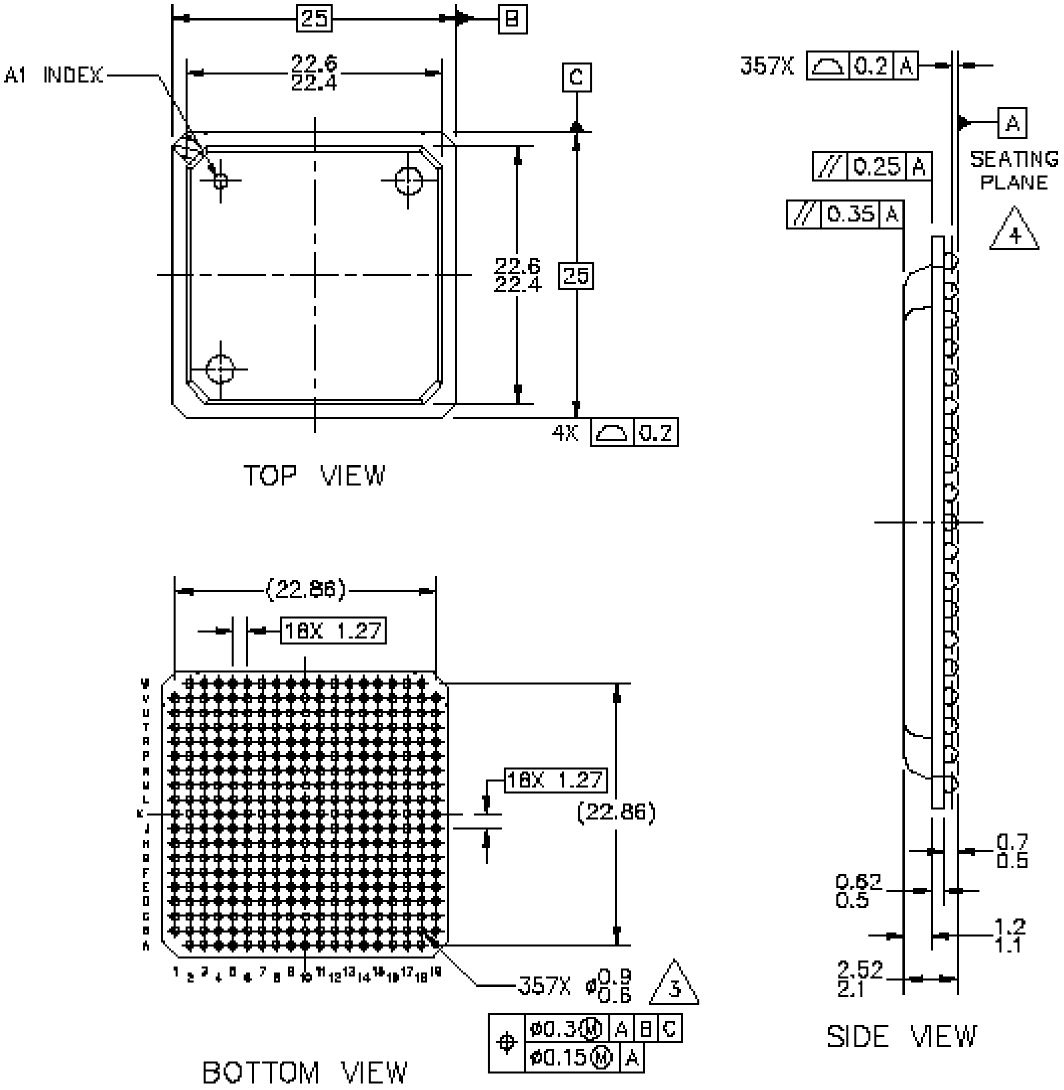
Figure 73. MII Transmit Signal Timing Diagram

Table 34. MPC860 Family Package/Frequency Availability (continued)

Package Type	Freq. (MHz) / Temp. (Tj)	Package	Order Number
Ball grid array *(continued)* ZP suffix—leaded ZQ suffix—leaded VR suffix—lead-free	80 0° to 95°C	ZP/ZQ[1]	MPC855TZQ80D4 MPC860DEZQ80D4 MPC860DTZQ80D4 MPC860ENZQ80D4 MPC860SRZQ80D4 MPC860TZQ80D4 MPC860DPZQ80D4 MPC860PZQ80D4
		Tape and Reel	MPC860PZQ80D4R2 MPC860PVR80D4R2
		VR	MPC855TVR80D4 MPC860DEVR80D4 MPC860DPVR80D4 MPC860ENVR80D4 MPC860PVR80D4 MPC860SRVR80D4 MPC860TVR80D4
Ball grid array (CZP suffix) CZP suffix—leaded CZQ suffix—leaded CVR suffix—lead-free	50 –40° to 95°C	ZP/ZQ[1]	MPC855TCZQ50D4 MPC855TCVR50D4 MPC860DECZQ50D4 MPC860DTCZQ50D4 MPC860ENCZQ50D4 MPC860SRCZQ50D4 MPC860TCZQ50D4 MPC860DPCZQ50D4 MPC860PCZQ50D4
		Tape and Reel	MPC855TCZQ50D4R2 MC860ENCVR50D4R2
		CVR	MPC860DECVR50D4 MPC860DTCVR50D4 MPC860ENCVR50D4 MPC860PCVR50D4 MPC860SRCVR50D4 MPC860TCVR50D4
	66 –40° to 95°C	ZP/ZQ[1]	MPC855TCZQ66D4 MPC855TCVR66D4 MPC860ENCZQ66D4 MPC860SRCZQ66D4 MPC860TCZQ66D4 MPC860DPCZQ66D4 MPC860PCZQ66D4
		CVR	MPC860DTCVR66D4 MPC860ENCVR66D4 MPC860PCVR66D4 MPC860SRCVR66D4 MPC860TCVR66D4

[1] The ZP package is no longer recommended for use. The ZQ package replaces the ZP package.

Figure 78 shows the mechanical dimensions of the ZQ PBGA package.



NOTE

1. All Dimensions in millimeters.
2. Dimensions and tolerance per ASME Y14.5M, 1994.
3. Maximum Solder Ball Diameter measured parallel to Datum A.
4. Datum A, the seating plane, is defined by the spherical crowns of the solder balls.

Figure 78. Mechanical Dimensions and Bottom Surface Nomenclature of the ZQ PBGA Package

15 Document Revision History

Table 35 lists significant changes between revisions of this hardware specification.

Table 35. Document Revision History

Revision	Date	Changes
10	09/2015	In Table 34, moved MPC855TCVR50D4 and MPC855TCVR66D4 under the extended temperature (–40° to 95°C) and removed MC860ENCVR50D4R2 from the normal temperature Tape and Reel.
9	10/2011	Updated orderable part numbers in Table 34, “MPC860 Family Package/Frequency Availability.”
8	08/2007	• Updated template. • On page 1, added a second paragraph. • After Table 2, inserted a new figure showing the undershoot/overshoot voltage (Figure 1) and renumbered the rest of the figures. • In Figure 3, changed all reference voltage measurement points from 0.2 and 0.8 V to 50% level. • In Table 16, changed num 46 description to read, “$\overline{\text{TA}}$ assertion to rising edge ...” • In Figure 46, changed $\overline{\text{TA}}$ to reflect the rising edge of the clock.
7.0	9/2004	• Added a tablefootnote to Table 6 DC Electrical Specifications about meeting the VIL Max of the I2C Standard • Replaced the thermal characteristics in Table 4 by the ZQ package • Add the new parts to the Ordering and Availablity Chart in Table 34 • Added the mechanical spec of the ZQ package in Figure 78 • Removed all of the old revisions from Table 5
6.3	9/2003	• Added Section 11.2 on the Port C interrupt pins • Nontechnical reformatting
6.2	8/2003	• Changed B28a through B28d and B29d to show that TRLX can be 0 or 1 • Changed reference documentation to reflect the Rev 2 MPC860 PowerQUICC Family Users Manual • Nontechnical reformatting
6.1	11/2002	• Corrected UTOPIA RXenb* and TXenb* timing values • Changed incorrect usage of Vcc to Vdd • Corrected dual port RAM to 8 Kbytes
6	10/2002	• Added the MPC855T. Corrected Figure 26 on page -36.
5.1	11/2001	• Revised template format, removed references to MAC functionality, changed Table 7 B23 max value @ 66 MHz from 2ns to 8ns, added this revision history table